

ABSTRACT OF THE DISCLOSURE

METHOD AND APPARATUS FOR RESIN-SEALING ELECTRONIC COMPONENTS

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[ABSTRACT]

[OBJECT]

The invention is directed at reducing overall production costs of a resin-sealing apparatus and simplifying maintenance work for the apparatus by
10 employing a facilitated resin-sealing method and a simplified molding die structure to handle a high-fluidity resin material.

[SOLUTION]

The apparatus has resin-sealing dies including an upper die 5 and a lower die 8, wherein the upper die 5 and the lower die 8 are opened and closed by
15 a die opening/closing mechanism. A cavity block 16 is disposed on a die surface of the upper die 5 in a manner that is allowed to move in a die opening/closing direction by a floating mechanism having floating pins 18. A cavity 20 and an air vent groove 22 communicating with the cavity 20 are formed in a die surface of the cavity block 16. A fit-in hole 24 is formed in a connected portion of the
20 cavity 20 and the air vent groove 22 along the die opening/closing direction. An air vent block 23 is disposed on a floating pin holder 17 corresponding to the fit-in hole 24 along the die opening/closing direction. The air vent block 23 is slidably and closely fitted in the fit-in hole 24.

[SELECTED DRAWING] Fig. 7